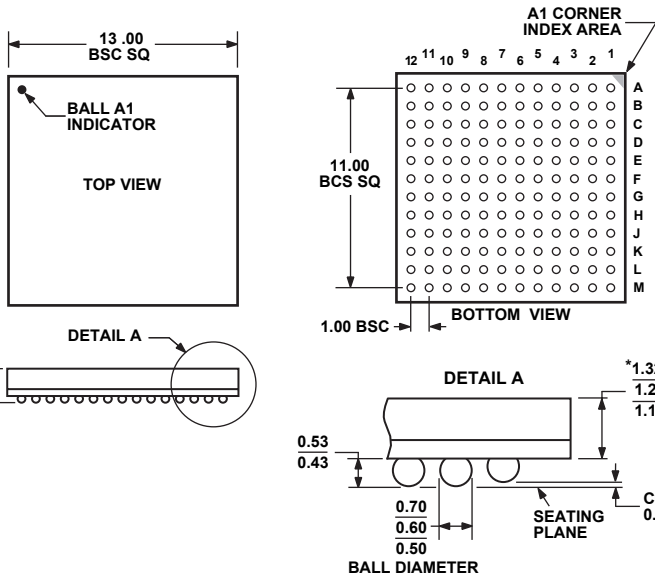


144-Ball Chip Scale Package Ball Grid Array [CSP_BGA]

(BC-144-3)

Dimensions shown in millimeters

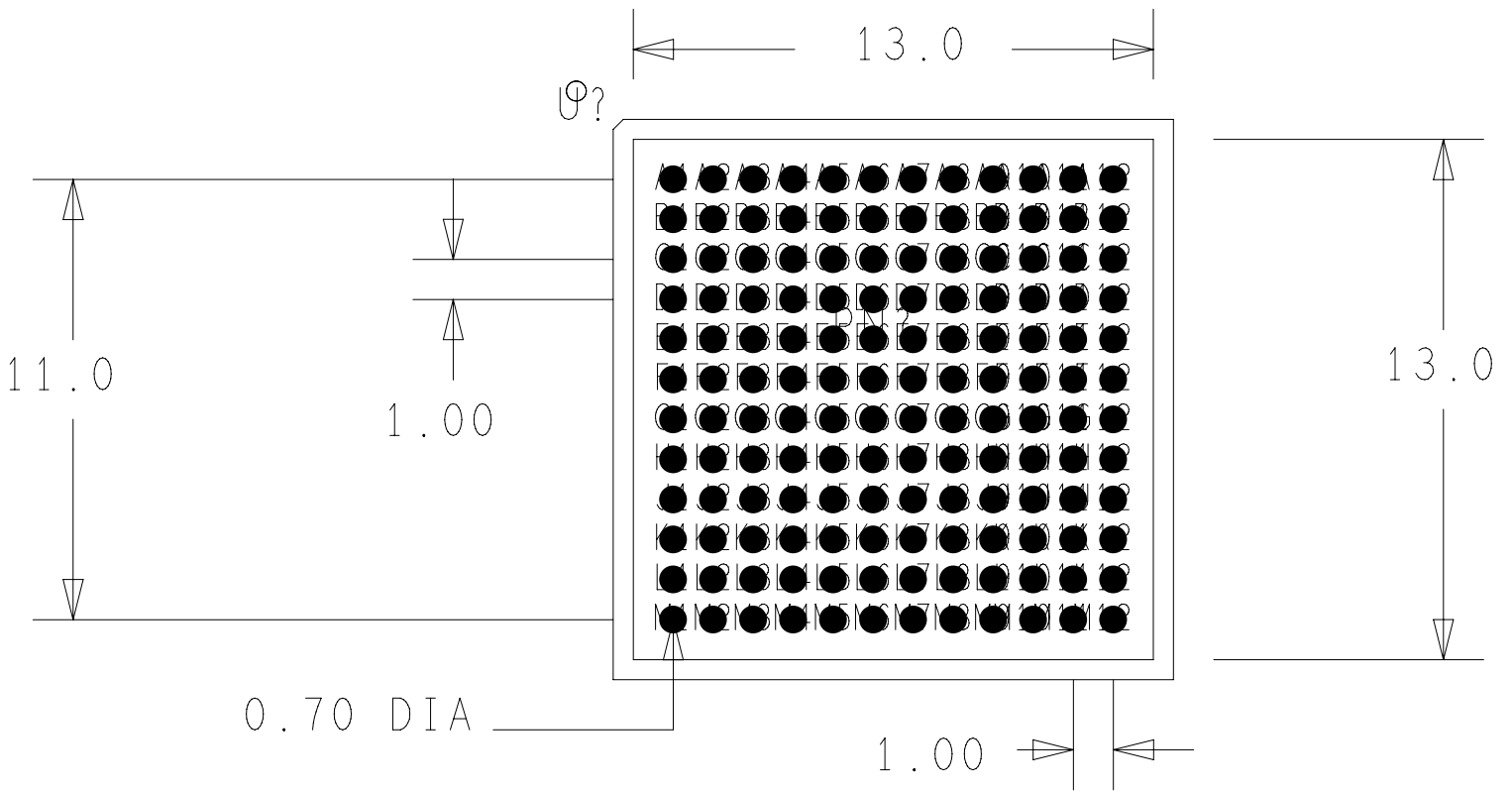


*COMPLIANT WITH JEDEC STANDARDS MO-192-AAD-1 WITH
EXCEPTION TO PACKAGE HEIGHT AND THICKNESS.

Analog Devices

BC - 144 - 3

REV A



(Dim. are in MM)

LAST MODIFIED 08/31/07